

In the Claims:

1. (Currently amended) A method of sealing two substrates in a microstructure, ~~characterized in that it comprises~~ comprising the following steps:

~~there is deposited~~ depositing a first rim onto the a surface of a first substrate (20) a, said first rim (22) comprising an "upper" upper rim (22B) consisting of comprising a layer of sealing material adapted to interdiffuse that interdiffuses spontaneously with the a material of the a second substrate (30) and a "lower" lower rim (22A) consisting of comprising an adhesion material adapted to cause that adheres said first substrate (20) ~~to adhere to said sealing material;~~ and there is deposited

depositing a second rim onto the a surface of at least one protuberance (36) formed on said second substrate (30) facing the said first rim (22), a said second rim (32) consisting of comprising a layer of said sealing material;

~~the two portions to be assembled are brought~~ bringing said upper rim and said second rim into contact; and

~~the heating said sealing material region is heated to obtain the interdiffusion of the interdiffuse said sealing material and the said material of the said second substrate (30).~~

2. (Currently amended) The Sealing sealing method according to claim 1, ~~characterized in that wherein~~ wherein said sealing material and the a material of said first substrate (20) are ~~able to comprise materials that~~ diffuse into each other and ~~in that wherein~~ wherein said lower rim (22A) forms a barrier to this diffusion.

3. (Currently amended) The Sealing sealing method according to claim 1, ~~characterized in that wherein~~ wherein said sealing material and the a material of said first substrate (20) ~~are able to diffuse~~ comprise materials that diffuse into each other and ~~in that wherein~~ wherein said first rim (22) further comprises a layer forming a barrier to this diffusion between said lower rim (22A) and said upper rim (22B).

4. (Currently amended) The Sealing sealing method according to any preceding claim 1, ~~characterized in that the wherein said first substrate (20) is of comprises~~ silicon.

5. (Currently amended) The Sealing sealing method according to any preceding claim 1, ~~characterized in that the wherein said second substrate (30) is of comprises~~ silicon.

6. (Currently amended) The Sealing sealing method according to any preceding claim 1, characterized in that wherein said sealing material is comprises gold.

7. (Currently amended) The Sealing sealing method according to claim 2 or claim 3, characterized in that wherein said barrier layer is of comprises tungsten.

8. (Currently amended) A Sealing sealing region between two substrates of a microstructure, characterized in that wherein said sealing region is obtained made by means of a the method according to any preceding claim 1.

9. (Currently amended) A Sealing sealing region between two substrates of a microstructure, characterized in that it comprises at least the following portions comprising:

~~on a first substrate (20), a "lower" lower rim (22A) on a first substrate consisting of, the lower rim comprising an adhesion material adapted to cause that adheres~~ said first substrate (20) to adhere to a sealing material adapted to interdiffuse that interdiffuses spontaneously with the a material of the a second substrate (30);

~~on said lower rim (22A), a layer of said sealing material on said lower rim;~~ and

~~on said sealing material layer, a protuberance (36) formed on said second substrate (30), said protuberance and containing a certain quantity of sealing material and contacting said layer of sealing material.~~

10. (Currently amended) The Sealing sealing region according to claim 9, characterized in that wherein said sealing material and the a material of said first substrate (20) are able to diffuse into each other and in that wherein said lower rim (22A) forms a barrier to this diffusion.

11. (Currently amended) The Sealing sealing region according to claim 9, characterized in that wherein said sealing material and the a material of said first substrate (20) are able to diffuse into each other and in that wherein said sealing region further comprises a layer forming a barrier to this diffusion between said lower rim (22A) and said layer of sealing material.

12. (Currently amended) The Sealing sealing region according to ~~any of claims claim 8 to 11, characterized in that wherein said surface of the said protuberance (36) is not plane, but features a certain comprising a number plurality~~ of hollows (39).

13. (Currently amended) The Sealing sealing region according to ~~any of claims claim 8 to 12, characterized in that the wherein said~~ surface of said protuberance (36) has comprises a meshed structure.

14. (Currently amended) The Sealing sealing region according to ~~any of claims claim 8 to 13, characterized in that the wherein said~~ first substrate (20) is of comprises silicon.

15. (Currently amended) The Sealing sealing region according to ~~any of claims claim 8 to 14, characterized in that the wherein said~~ second substrate (30) is of comprises silicon.

16. (Currently amended) The Sealing sealing region according to ~~any of claims claim 8 to 15, characterized in that wherein said sealing material is~~ comprises gold.

17. (Currently amended) The Sealing sealing region according to ~~any of claims claim 10 or claim 14, characterized in that wherein said barrier layer is of~~ comprises tungsten.

18. (Currently amended) A microstructure Microstructure comprising a sealing region according to ~~any of claims claim 8 to 17.~~

19. (New) The sealing method according to claim 3, wherein said barrier comprises tungsten.

20. (New) The sealing region according to claim 9, wherein said surface of said protuberance comprises a plurality of hollows.

21. (New) The sealing region according to claim 9, wherein said surface of said protuberance comprises a meshed structure.

22. (New) The sealing region according to claim 9, wherein said first substrate comprises silicon.

23. (New) The sealing region according to claim 9, wherein said second substrate comprises silicon.

24. (New) The sealing region according to claim 9, wherein said sealing material comprises gold.

25. (New) The sealing region according to claim 11, wherein said barrier comprises tungsten.